

60V N-Channel MOSFET
Product Summary

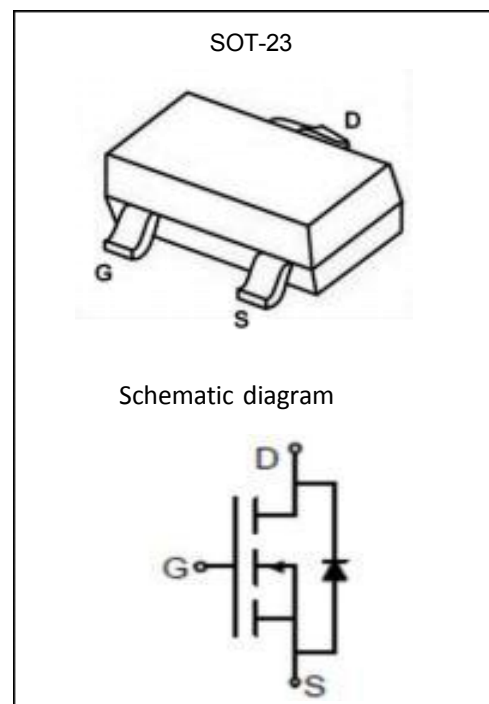
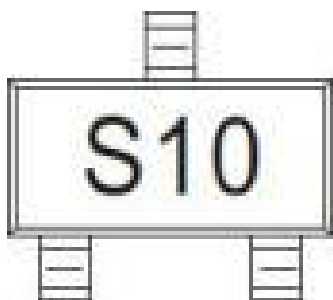
$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
60V	105mΩ@10V	3A
	125mΩ@4.5V	

Feature

- High power and current handling capability
- Surface mount package

Application

- Battery Switch
- DC/DC Converter

MARKING:

ABSOLUTE MAXIMUM RATINGS ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

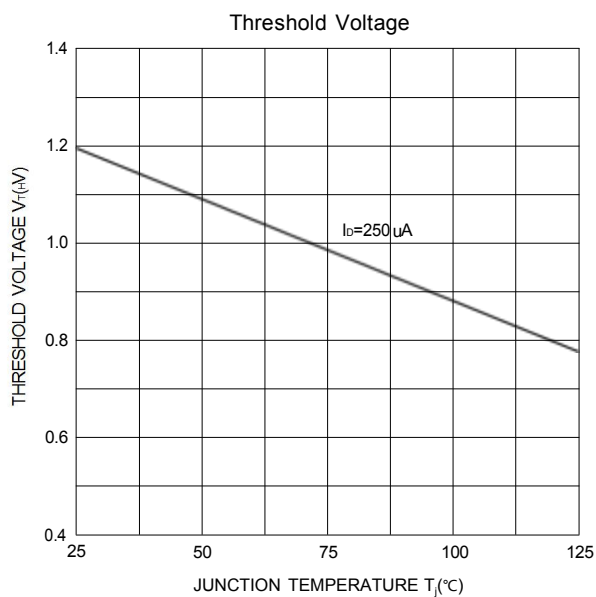
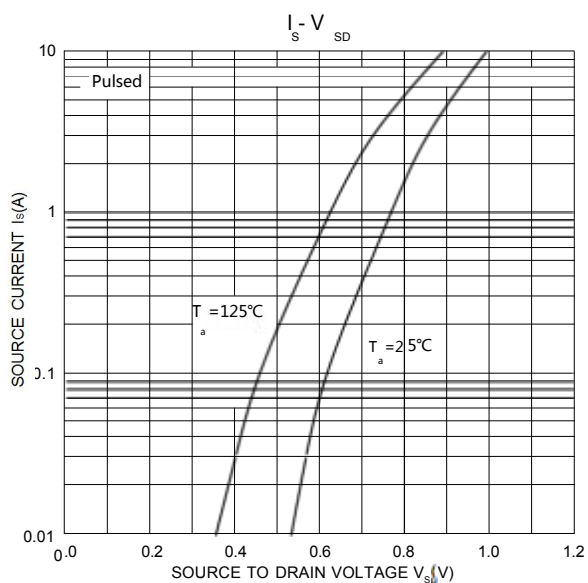
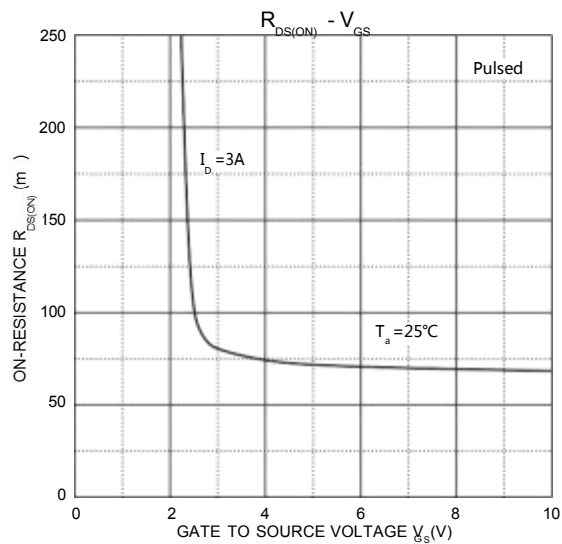
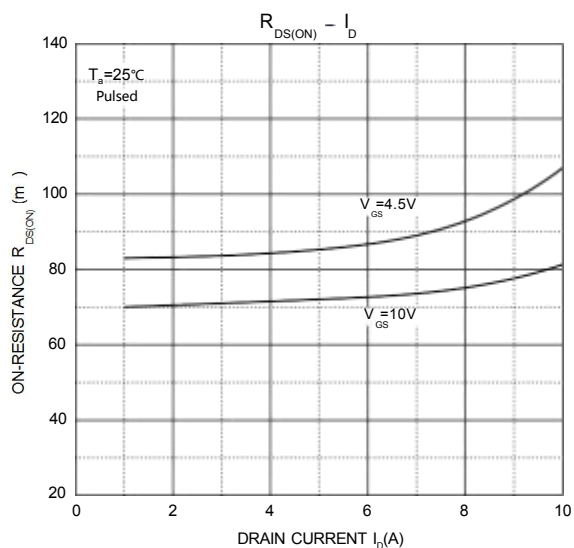
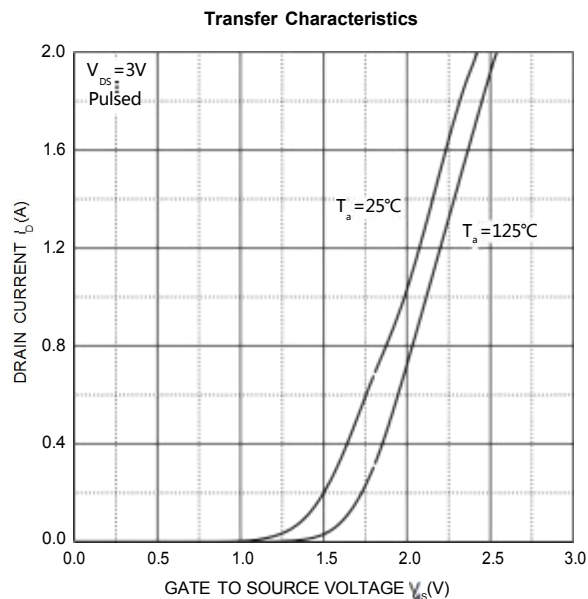
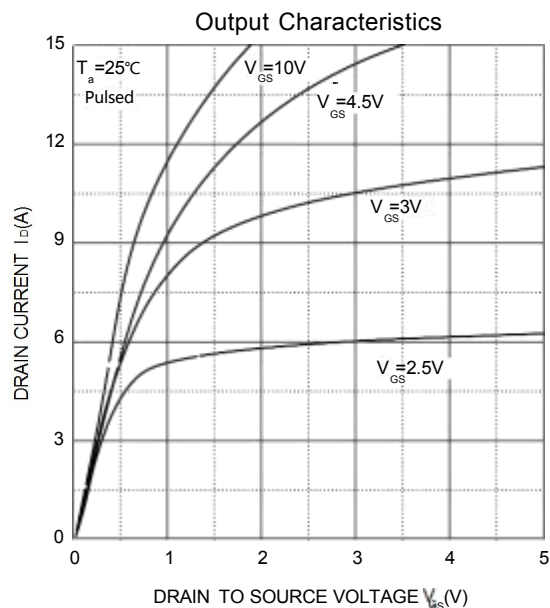
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	
Continuous Drain Current	I_D	3	A
Pulsed Drain Current ¹	I_{DM}	10	
Maximum Power Dissipation	P_D	0.35	W
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	357	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~ +150	

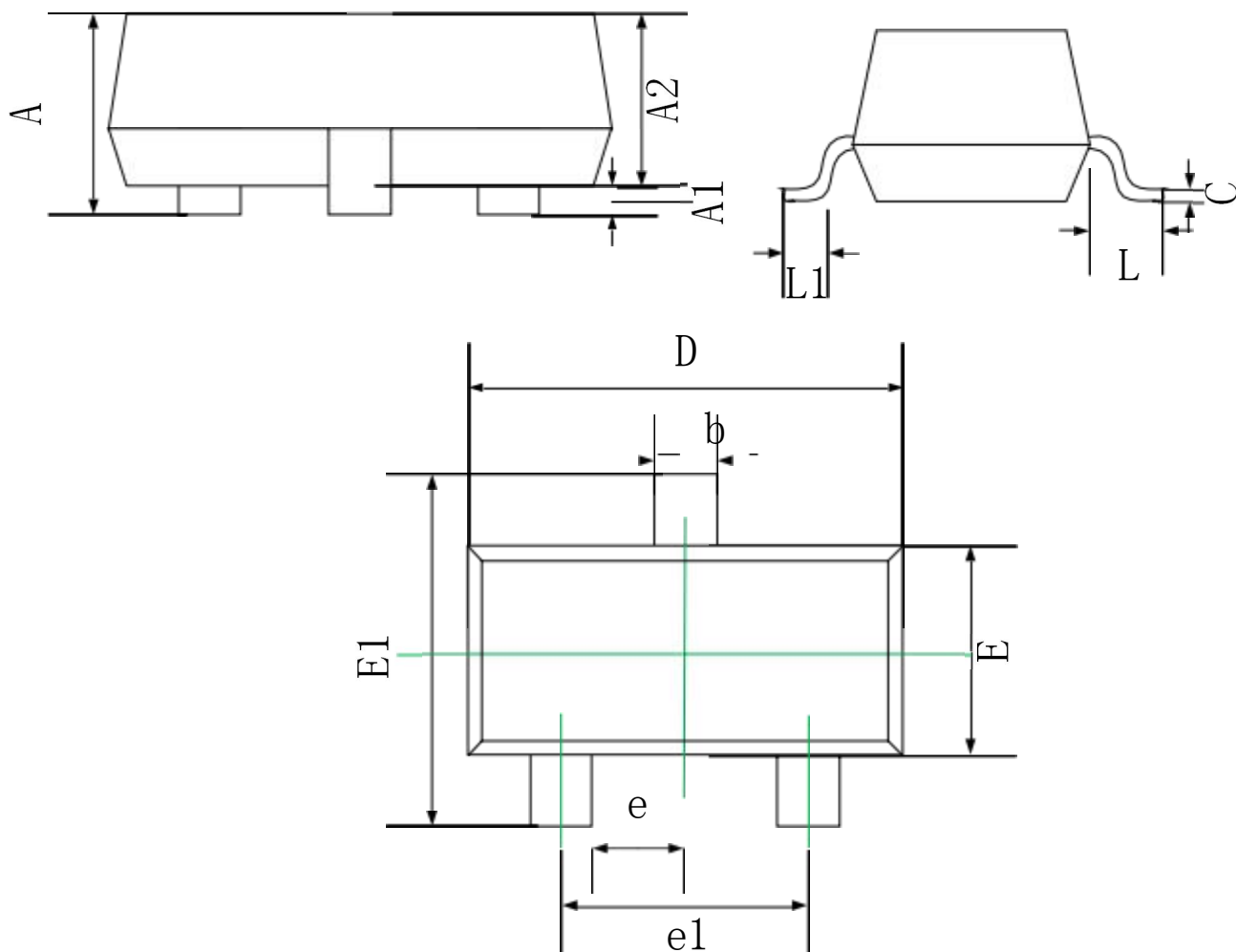
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} = 0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±100	nA
Gate Threshold Voltage ³	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	1.2	2	V
Drain-Source On-Resistance ³	R _{DS(on)}	V _{GS} =10V, I _D =3A		70	105	mΩ
		V _{GS} =4.5V, I _D =3A		82	125	
Forward Tranconductance ³	g _{FS}	V _{DS} =15V, I _D =2A	1.4	2.5		S
DYNAMIC CHARACTERISTICS ⁴						
Input Capacitance	C _{iss}	V _{DS} =30V,V _{GS} =0V,f =1MHz		250		pF
Output Capacitance	C _{oss}			26		
Reverse Transfer Capacitance	C _{rss}			20		
SWITCHING CHARACTERISTICS ⁴						
Total Gate Charge	Q _g	V _{DS} =30V,V _{GS} =4.5V,I _D =3A		7		nC
Gate-Source Charge	Q _{gs}			1.2		
Gate-Drain Charge	Q _{gd}			1.5		
Turn-On Delay Time	t _{d(on)}	V _{GS} =10V,V _{DD} =30V,I _D =1.5A,R _{GEN} =1Ω		6.5		ns
Turn-On Rise Time	t _r			15.2		
Turn-Off Delay Time	t _{d(off)}			15.2		
Turn-Off Fall Time	t _f			10.3		
Source-Drain Diode characteristics ⁴						
Body Diode Voltage	V _{SD}	I _S =3A,V _{GS} =0V		0.8	1.2	V

Notes :

1. Repetitive rating : Pulse width limited by junction temperature.
2. Surface mounted on FR4 board , t≤10s.
3. Pulse Test : Pulse Width≤300μs, Duty Cycle≤0.5%.
4. Guaranteed by design, not subject to producing.

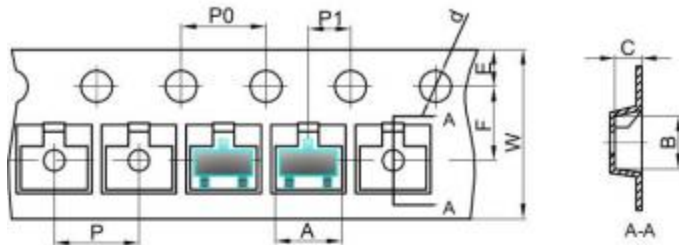
Typical Characteristics


SOT-23 Package Information


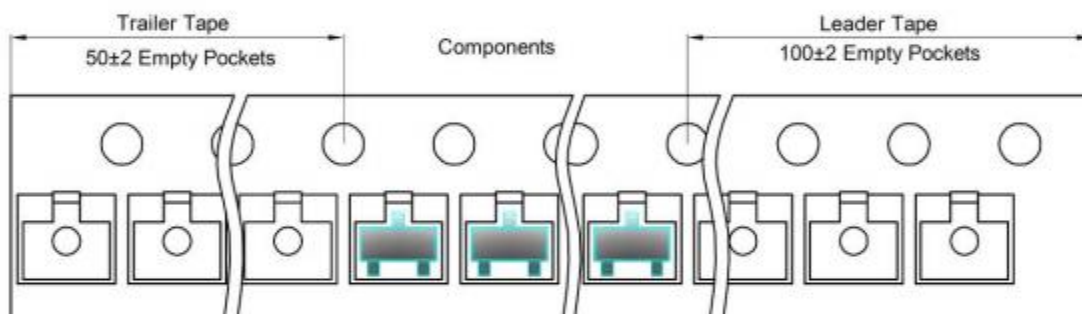
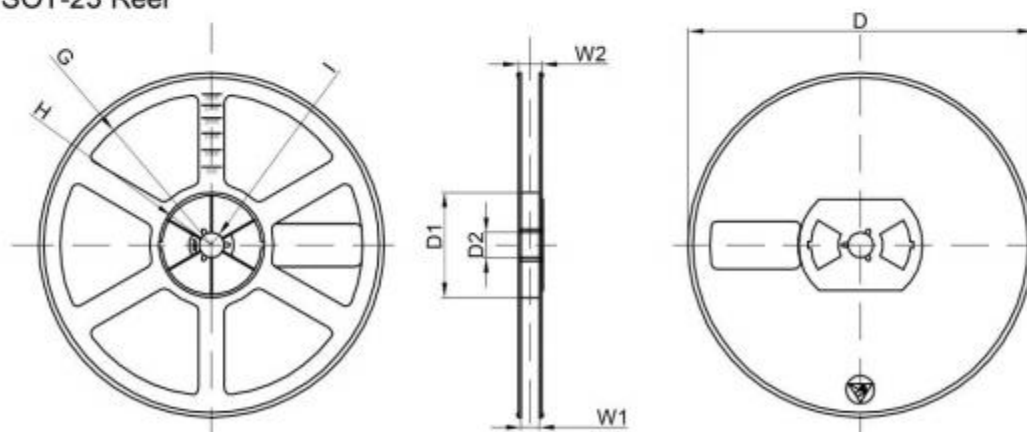
Symbol	Dimensions In Millimeters	
	Min.	Max.
A	0.90	1.15
A1	0.00	0.10
A2	0.90	1.05
b	0.30	0.50
c	0.08	0.15
D	2.80	3.00
E	1.20	1.40
E1	2.25	2.55
e	0.95 REF.	
e1	1.80	2.00
L	0.55 REF.	
L1	0.30	0.50

SOT-23 Tape and Reel
SOT-23 Tape and reel

SOT-23 Embossed Carrier Tape



Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23 Tape Leader and Trailer

SOT-23 Reel


Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	

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